

ON Semiconductor				10/15/2019
Base Part		US1DFA	HF	
Orderable Part		US1DFA	Total weight (mg)	18.791563
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.72998	Silicon (Si)	7440-21-3	90.00027692
		Nickel (Ni)	7440-02-0	0.64984815
		Gold (Au)	7440-57-5	0.14984661
		Lead Bisilicate	65997-18-4	9.20002831
Die Attach Solder	4.11996	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	6.79991	Iron (Fe)	7439-89-6	0.1
		Copper (Cu)	7440-50-8	99.87
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	6.941643	Ortho Cresol Novolac Resin	29690-82-2	15.45040562
		Carbon Black (C)	1333-86-4	1.03002992
		Phenolic Resin (Novolac)	9003-35-4	10.30027041
		Silica Crystalline (SiO2)	14808-60-7	73.21929405
Plating	0.20007	Tin (Sn)	7440-31-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				